WHAT IS CLAIMED IS:

1. A radio frequency coupler, comprising:

a dielectric substrate;

a pair of strip conductors disposed over an upper surface of the dielectric substrate, a first portion of the pair of strip conductors being in an overlying relationship and separated by a first dielectric layer to provide a coupling region between the portion of the pair of strip conductors in the overlying relationship; a second portion of the pair of strip conductors being disposed on the upper surface of substrate;

a pair of opposing ground pads disposed on, and separated by, different portions of the upper surface of the substrate, the coupling region being disposed between the pair of opposing ground pads;

a second dielectric layer disposed over the coupling region and between the pair of opposing grond pads;

an electrically conductive shield layer disposed over the second dielectric layer, extending over opposing sides of the second dielectric layer and onto the pair of opposing ground pads.

2. The radio frequency coupler recited in claim 1 including a second pair of ground pads disposed on , and separated by, different portions the upper surface of the substrate, the coupling region being disposed between the second pair of ground pads, the first-mentioned pair of ground pads, the first-mentioned pair of ground pads and the second pair of ground pads being disposed along perpendicular lines, the electrically conductive shield layer being disposed over a second pair of opposing sides of the dielectric layer and onto the second pair of ground pads.

3. A radio frequency coupler, comprising:

a dielectric substrate;

a first metal layer disposed on an upper surface of the substrate, the first metal layer being patterned to provide:

a pair of ground pads disposed on, and separated by, different portions of the dielectric substrate;

a first lower strip conductor, spaced from the pair of ground pads, having: an input at first end, an output at a second end; and, a coupling region disposed between the first end, the second end, and between the pair of ground pads;

a second lower strip conductor having: an input end and an output end; and,

a third lower strip conductor having an input end and an output end;

a first dielectric layer disposed over the coupling region;

a second metal layer configured as a strip conductor disposed on the first dielectric layer over the coupling region, the second metal layer having one end disposed on, and electrically connected to, the output end of the second lower strip conductor and having a second end disposed on, and electrically connected to the input end of the third lower strip conductor; and

a second dielectric layer is disposed over the second metal layer and between the pair of ground pads; and

an electrically conductive shield layer disposed on an upper surface of the second dielectric layer extending over sides of the second dielectric layer and onto the pair of ground pads.

4. The radio frequency coupler recited in claim 3 wherein the first metal layer is patterned to provide a second pair of ground pads on, and separated by, different portions of the upper surface of the dielectric substrate; the coupling region being disposed between the second pair of ground pads, the first-mentioned pair of ground pads, the first-mentioned pair of ground pads and the second pair of ground pads being disposed along perpendicular lines, the electrically conductive shield layer being disposed over a second pair of opposing sides of the dielectric layer and onto the second pair of ground pads.

5. A method for tuning a radio frequency coupler, comprising:

(a) providing a radio frequency coupler comprising: a dielectric substrate; a pair of strip conductors disposed over an upper surface of the dielectric substrate, a first portion of the pair of strip conductors being in an overlying relationship and separated by a first dielectric layer to

provide a coupling region between the portion of the pair of strip conductors in the overlying relationship; a second portion of the pair of strip conductors being disposed on the upper surface of substrate; and a pair of opposing ground pads disposed on the upper surface of the substrate, the coupling region being disposed between the pair of opposing ground pads;

(b) measuring a degree coupling between the pair of strip conductors;

(c) comparing the measured degree of coupling with a predetermined degree of coupling;

(d) adjusting a width of an upper one of the pair of strip conductors widths;

(e) repeating (b) through (d) until the degree of coupling reaches the predetermined degree coupling.

6. The radio frequency coupler recited in claim 1 wherein the electrically conductive shield layer is a conductive ink.

7. The radio frequency coupler recited in claim 2 wherein one of the second portion of the pair of strip conductors pass between one of the first mentioned pair of ground pads and one of the second pair of ground pads.

8. The radio frequency coupler recited in claim 7 wherein a second one of the second portion of the pair of strip conductors pass between a second one of the first mentioned ground pads and a second one of the second pair of ground pads.

9. The radio frequency coupler recited in claim 3 wherein the electrically conductive shield layer is a conductive ink.

10. The radio frequency coupler recited in claim 4 wherein one of the first lower strip conductors pass between one of the first mentioned pair of ground pads and one of the second pair of ground pads.

11. The radio frequency coupler recited in claim 10 wherein a second one of the second lower strip conductors pass between a second one of the first mentioned and a second one of the second pair of ground pads.

12. The radio frequency coupler recited in claim 1 wherein portions of the electrically conductive shield layer are disposed on sides of the first dielectrics layer and sides of the second dielectric layer and over on portions of the upper surface of the dielectric substrate.

13. The radio frequency coupler recited in claim 3 wherein the portions of the electrically conductive shield layer are disposed on sides of the first dielectrics layer and sides of the second dielectric layer and over portions of the upper surface of the dielectric substrate.

14. The radio frequency coupler recited in claim 12 including a second pair of ground pads disposed on , and separated by, different portions the upper surface of the substrate, the coupling region being disposed between the second pair of ground pads, the first-mentioned pair of ground pads, the first-mentioned pair of ground pads and the second pair of ground pads being disposed along perpendicular lines, the electrically conductive shield layer being disposed over a second pair of opposing sides of the dielectric layer and onto the second pair of opposing ground pads.

15. The radio frequency coupler recited in claim 14 wherein a first one of the second portion of the pair of strip conductors pass between one of the first mentioned pair of ground pads and one of the second pair of ground pads.

16. The radio frequency coupler recited in claim 15 wherein a second one of the second portion of the pair of strip conductors pass between a second one of the first mentioned ground pads and a second one of the second pair of ground pads.

17. The radio frequency coupler recited in claim 15 wherein the electrically conductive shield layer is a conductive ink.

18. The radio frequency coupler recited in claim 16 wherein the electrically conductive shield layer is a conductive ink.